

MANUFACTURE OF SEMICONDUCTOR PACKAGE AND SEMICONDUCTOR PACKAGE

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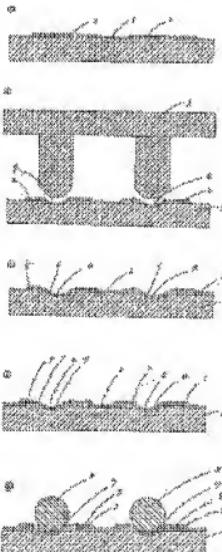
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Abstract of JP 10154766 (A)

PROBLEM TO BE SOLVED: To arrange solder balls with good accuracy and also to inhibit the balls from rolling by a method wherein recessed parts are formed in ball pad lands to be mounted with the solder balls and mounting parts for the solder balls are made to expose through resists. **SOLUTION:** Recessed parts 4 are respectively formed in the centers of ball pad lands 2 formed on a wiring board 1 by metallic molding. Resists 5 are applied on the board 1 with the recessed parts 4 formed therein. The resists 5 are exposed without being applied on mounting parts 6, on which the balls 8 are mounted, on the lands 2. An Au-Ni plating 7 is applied to the mounting parts 6 for the solder balls 8. Then, the solid solder balls 8 are arranged on the mounting parts 6 for the solder balls 8. The surfaces of the arranged solder balls 8 surface-contact the recessed part 4 formed in the lands 2.; The mounting positions of the balls 8 are accurately positioned by the recessed parts 4 and at the same time, the resists 5, through which the mounting parts 6 only are exposed, prevent the balls 8 from rolling.



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